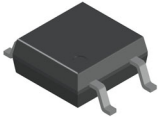
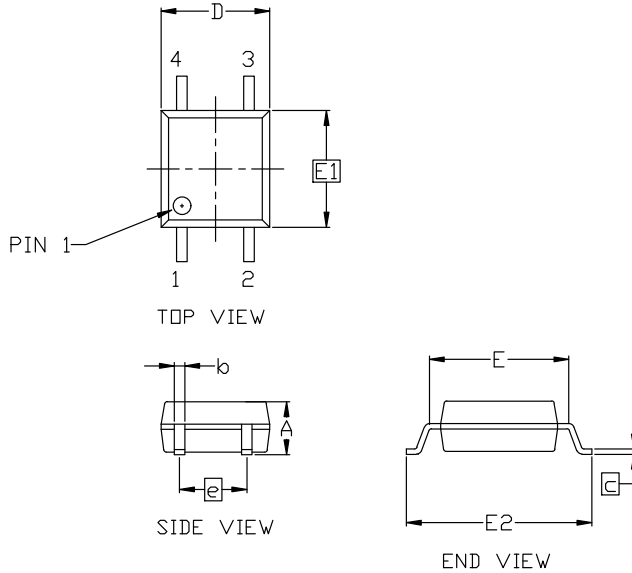


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



MFP4 4.1x4.4, 2.54P
CASE 100EC
ISSUE O

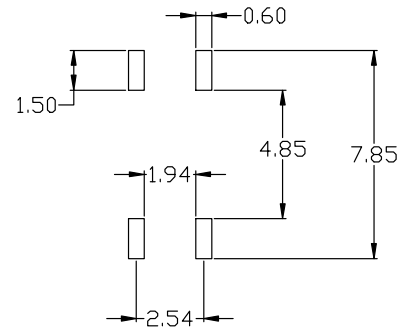
DATE 08 SEP 2022



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	2.00
b	0.30	0.40	0.50
c	0.20 REF		
D	3.90	4.10	4.30
E	5.00	5.20	5.40
E1	4.40 TYP		
E2	6.70	7.00	7.30
e	2.54 TYP		



RECOMMENDED
 MOUNTING
 FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	MFP4 4.1x4.4, 2.54P	PAGE 1 OF 1

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